

1

2

3

4

5

6

7

8

ROHS CONFORM

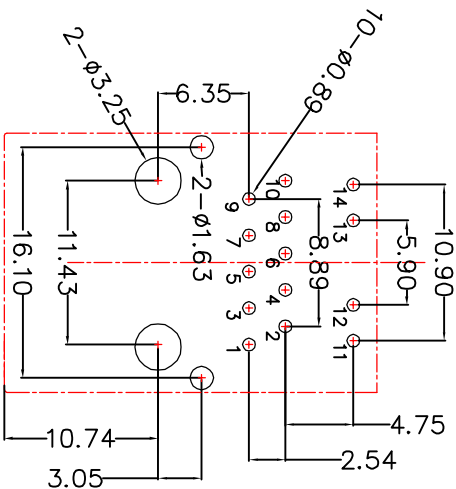
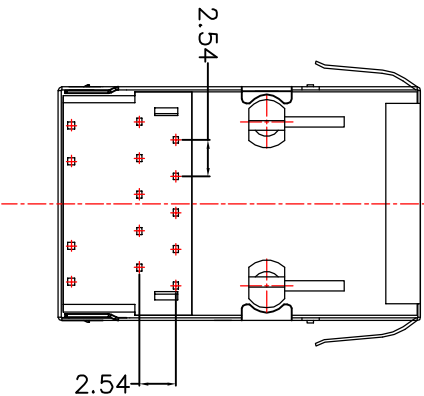
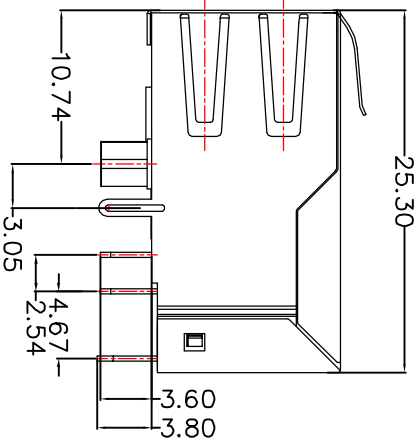
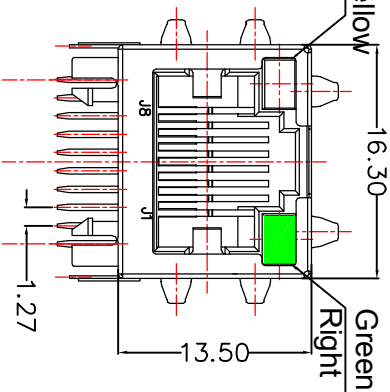
REV.	ECN / DESCRIPTION	BY	DATE

Material:

Housing :PBT+30%GF,UL94V-0,Black.
Plastic bracket :PBT+30%GF,UL94V-0,Black.
Shell: C2680R-H,T=0.20mm,Nickel plated on all area.
Contact terminal: Phosphor bronze C5210R-EH,T=0.35mm,
Gold plated 6u" on mating area.
Solder terminal:Brass,C2680-H,T=0.35mm,Tin plated
80u"Min. on solder area.

Mechanical:

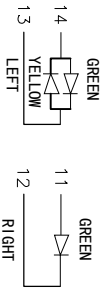
Durability :750 cycles Min.
Mating force :22N Max.
Operating temperature:-40°C~+85°C.
Storage temperature: : -40°C~+85°C.



PCB LAYOUT

Specification LED

Standard LED Color	LED Wavelength	Forward(V MAX)	Typical(V TYP)	Luminous Intensity
Green	560-566nm	2.5v	2.1-2.2v	9-25 MCD
Yellow	580-610nm	2.5v	2.1-2.2v	9-30 MCD



TITLE:

TAB-UP 1X1 1000BASE

SIZE

A4

UNITS

MM[INCH]

GENERAL TOLERANCES

UNLESS SPECIFIED

APPROVED BY:

JP.Gong

PART NO.:

L-KLS12-TL191-1X1-GY/G-03

SACLE

1:1

REV

A0

X $\pm$ 0.25

X $\pm$ 2.0°

CHECKED BY:

XU.TW

DWG NO.:

SHEET

1/3

.XX $\pm$ 0.10

.XX° $\pm$ 1.5°

DESIGND BY:

Qu.mq

KLS ELECTRONIC CO., LTD

12345678

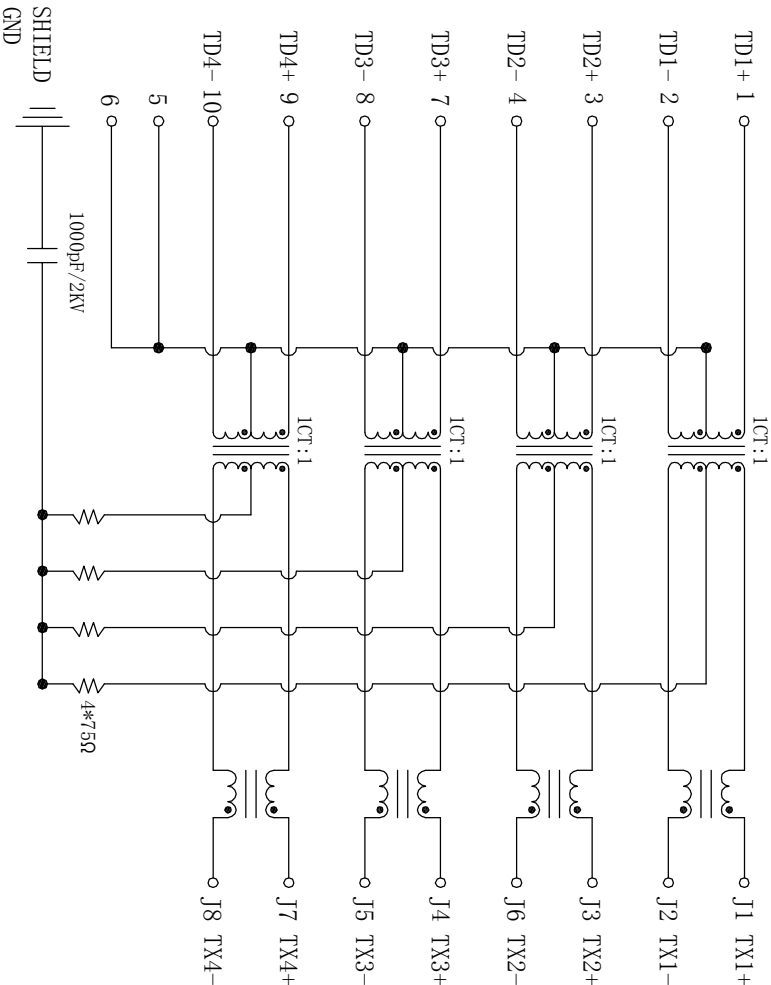
RoHS CONFORM

REV.	ECN / DESCRIPTION	BY	DATE

Electrical:

1. Voltage rating: 125V AC.
2. Insulation resistance: 500 megohms MIN @500VDC.
3. Contact resistance: 50 milliohms Max.
4. Turn Ratio: 1~2:J1~J2=1CT:1CT(±2%).
3~4:J3~J6=1CT:1CT(±2%).
7~8:J4~J5=1CT:1CT(±2%).
9~10:J7~J8=1CT:1CT(±2%).

5. OCL: 350uH Min at 100KHz 100mV 8mA DC.
6. Insertion Loss: -1.0 dB Max 1MHz to 100MHz.
7. Return loss: -16dB Min From 1MHz to 30MHz;
-14dB Min From 30MHz to 60MHz;
-10dB Min From 60MHz to 80MHz.
8. Cross talk: -40dB Min From 1MHz-30MHz;
-35dB Min From 30MHz-60MHz;
-30dB Min From 60MHz-100MHz;
9. CMR: -35dB Min From 1MHz-100MHz;
10. Hi-Pot: 1500V AC 6S 1mA



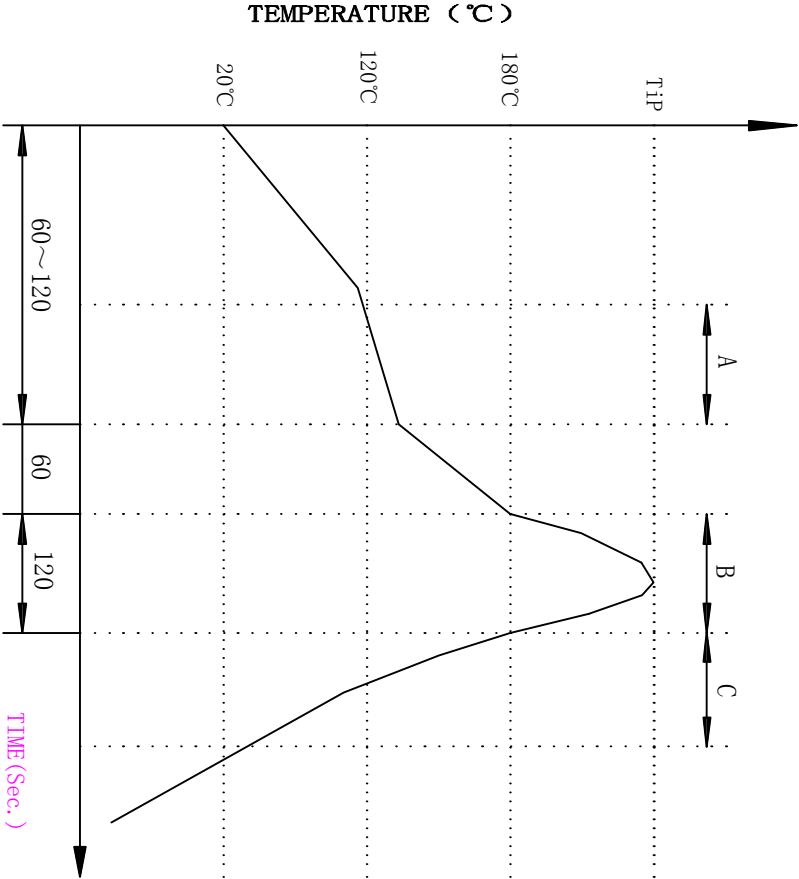
KLS ELECTRONIC CO., LTD

TITLE:		SIZE	UNITS	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY:
TAB-UP 1X1 1000BASE		A4	MM[INCH]			J.P. Gong
PART NO.:	L-KLS12-TL191-1X1-GY/G-03	SACLE	REV	CHECKED BY:		Xu. TW
DWG NO.:		1:1	A0	DESIGN BY:		Qu.mq
		SHEET				
		2/3				

ROHS CONFORM

PROFILE OF WAVE SOLDER

REV.	ECN / DESCRIPTION	BY	DATE



A.Preheating B.Soldering C.Gradual Cooling
Tip temperature:260±5°C.
Tip temperature time:5Sec Max.
Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

After the wave solder, the plastic column of product under the pcb will have a slight plastic melting situation .

TITLE:		SIZE	UNITS	GENERAL TOLERANCES UNLESS SPECIFIED			APPROVED BY:
TAB-UP 1X1 1000BASE		A4	MM[INCH]				JP.Gong
PART NO.:		SACLE	REV				CHECKED BY:
L-KLS12-TL191-1X1-GY/G-03		1:1	A0				Xu.TW
DWG NO.:		SHEET					DESIGND BY:
		3/3					Qu.mq

KLS ELECTRONIC CO., LTD